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Cash Dividend Announcement for Equity Issuer	
Issuer name	Hua Hong Semiconductor Limited
Stock code	01347
Multi-counter stock code and currency	Not applicable
Other related stock code(s) and name(s)	Not applicable
Title of announcement	Final Dividend for the Year Ended 31 December 2023
Announcement date	28 March 2024
Status	New announcement
Information relating to the dividend	
Dividend type	Final
Dividend nature	Ordinary
For the financial year end	31 December 2023
Reporting period end for the dividend declared	31 December 2023
Dividend declared	HKD 0.165 per share
Date of shareholders' approval	09 May 2024
Information relating to Hong Kong share register	
Default currency and amount in which the dividend will be paid	HKD 0.165 per share
Exchange rate	HKD 1 : HKD 1
Ex-dividend date	03 June 2024
Latest time to lodge transfer documents for registration with share registrar for determining entitlement to the dividend	04 June 2024 16:30
Book close period	From 05 June 2024 to 06 June 2024
Record date	06 June 2024
Payment date	26 June 2024
Share registrar and its address	Tricor Investor Services Limited
	17/F, Far East Finance Centre
	16 Harcourt Road
	Hong Kong
Information relating to withholding tax	
Details of withholding tax applied to the dividend declared	Not applicable

Page 1 of 2 v 1.1.1

Information relating to listed warrants / convertible securities issued by the issuer

Details of listed warrants / convertible securities issued by the issuer

Not applicable

Other information

Holders of shares in the Company listed on the Science and Technology Innovation Board of the Shanghai Stock Exchange (the "RMB Shares") should refer to announcement(s) which the Company may from time to time publish on the websites of the Shanghai Stock Exchange and the Company with respect to 2023 final dividend arrangements applicable to holders of RMB Shares.

Directors of the issuer

As at the date of this announcement, the Board of Directors of the Company comprises (i) Mr. Suxin Zhang and Mr. Tang Junjun as executive directors; (ii) Mr. Jun Ye, Mr. Guodong Sun, Mr. Limin Zhou and Ms. Chengyan Xiong as non-executive directors; and (iii) Mr. Stephen Tso Tung Chang, Mr. Kwai Huen Wong, JP and Mr. Songlin Feng as independent non-executive directors.

Page 2 of 2 v 1.1.1